

## ET1894

### End Termination

#### Description

ET1894 is low firing plateable silver end termination designed for application on to MLV chip components. The rheology is suitable for machining dipping applications.

#### Key Features

- Nickel plateable
- Excellent fired film density and adhesion



*This picture does not show the packaging of ET1894 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.*

#### Typical Properties

Viscosity	35-45 Kcps Brookfield RVT SC4-14 spindle, 6R utility cup at 10 rpm, 25 °C
Alloy Ratio	100
Metal	Ag

#### Recommended Processing Guide

Process Temperature (TDS)	560-580 °C peak temperature. Dwell time of 5-7 minutes at peak 45 minutes firing cycle.
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